

C0603X189BATAC7411

General Information

Series Style

Description

Features

SMD Comm X8G HT150C Flex, Ceramic, 1.8 pF, +/-0.1 pF, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm

SMD Comm X8G HT150C Flex

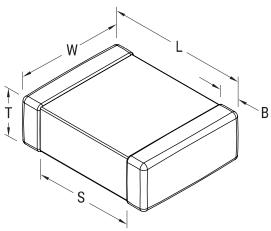
SMD, MLCC, High Temperature,

High Temperature, Ultra-Stable

SMD Chip

Ultra-Stable





<u> </u>		RoHS	Yes
		Termination	Flexible Termination
		Marking	No
S Click here for the 3D model.		AEC-Q200	No
		Typical Component Weight	4.6 mg
		Shelf Life	78 Weeks
		MSL	1
Dimensions		Specifications	
Chip Size	0603	Capacitance	1.8 pF
L	1.6mm +/-0.17mm	Measurement Condition	1 MHz 1.0Vrms

Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

Packaging Specifications		
Packaging	T&R, 330mm, Paper Tape	
Packaging Quantity	15000	

Specifications	
Capacitance	1.8 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.1 pF
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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